US-PICC2 based assemblies for card, module, and inlay production

More power than before and even more

Smartware is pleased to introduce assemblies based on the new US-PICC2 board.

The US-4P_SMB (4 contactless heads) and US-4P4I (4 combi heads) are designed to address all contactless cards whatever is the chip manufacturer or the antenna technology.

The multiple functionalities of the US-4P_SMB and the US-4P4I allow the personalization of contactless/combi cards & chip card modules, and also the personalization of rfid inlays while ensuring performance, reliability and flexibility.

Overview

The US-4P_SMB is an assembly using two US-PICC2 boards coupled with the powerful US-CORE V5. This product provides four 50Ω contactless interfaces.


Both products have been designed to be mounted into Smartware rack housings.

Same assemblies are available for OEM integration to fit into all manufacturing equipment.

Protect your investment

The US-4P_SMB and the US-4P4I assemblies follows the “Pay for what you use” SMARTWARE’s concept: Buy today one model and activate other functionalities later.

US-PICC2 Features

• Supported protocols: ISO 14443, VHBR
  ISO 15693, MIFARE™, MIFARE Plus™, FeliCa™
• Personalization of contactless chip card module
• 50Ω RF output impedance
• Adjustable RF output power
• RF demultiplexer 1:2 for each interface
• Same size as US-PICC V1

US-ICC2 Features

• Supported protocols: ISO 7816, SWP/SHDLC,
  Memory cards
• Personalization of contact chip card module
• Contact voltage up to 5.5Volts
• Adjustable communication up to 20MHz
• Continuity test
• Same size as US-PICC2

Addressed market

dual interface card
dual interface module
contactless module
rfid inlay